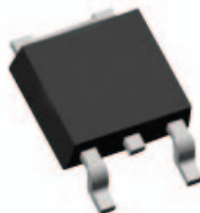
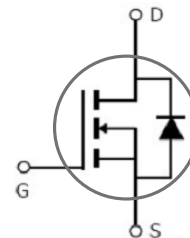


## Main Product Characteristics

$V_{(BR)DSS}$	650V
$R_{DS(ON)}$	0.57 $\Omega$
$I_D$	7A



TO-252 (DPAK)



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The SSFD7N65 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	650	V
Gate-Source Voltage	$V_{GS}$	$\pm 30$	V
Drain Current – Continuous ( $T_C=25^\circ\text{C}$ )	$I_D$	7	A
Drain Current – Continuous ( $T_C=100^\circ\text{C}$ )		4.4	A
Drain Current – Pulsed <sup>1</sup>	$I_{DM}$	28	A
Single Pulse Avalanche Energy <sup>2</sup>	$E_{AS}$	120	mJ
Single Pulse Avalanche Current <sup>2</sup>	$I_{AS}$	4.9	A
Power Dissipation ( $T_C=25^\circ\text{C}$ )	$P_D$	50	W
Power Dissipation – Derate above 25 $^\circ\text{C}$		0.4	W/ $^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-50 to +150	$^\circ\text{C}$
Operating Junction Temperature Range	$T_J$	-50 to +150	$^\circ\text{C}$

## Thermal Characteristics

Parameter	Symbol	Typ.	Max.	Unit
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	---	80	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction to Case	$R_{\theta JC}$	---	2.5	$^\circ\text{C}/\text{W}$

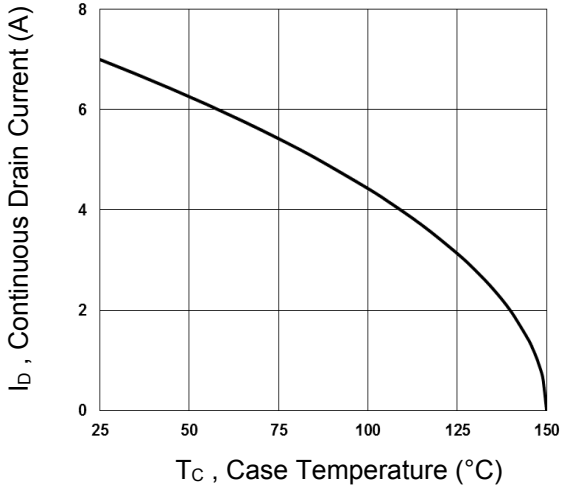

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	650	---	---	V
$BV_{DSS}$ Temperature Coefficient	$\Delta BV_{DSS}/\Delta T_J$	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.59	---	$V/^\circ\text{C}$
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=650V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	1	$\mu A$
		$V_{DS}=650V, V_{GS}=0V, T_J=125^\circ\text{C}$	---	10	---	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 30V, V_{DS}=0V$	---	---	$\pm 100$	nA
<b>On Characteristics</b>						
Static Drain-Source On-Resistance <sup>3</sup>	$R_{DS(ON)}$	$V_{GS}=10V, I_D=3.5A, T_J=25^\circ\text{C}$	---	0.47	0.57	$\Omega$
		$V_{GS}=10V, I_D=3.5A, T_J=150^\circ\text{C}$	---	1.9	---	$\Omega$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	2.5	3.5	4.5	V
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}$		---	-9.3	---	$\text{mV}/^\circ\text{C}$
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>3, 4</sup>	$Q_g$	$V_{DS}=480V, V_{GS}=10V, I_D=3.5A$	---	15	---	nC
Gate-Source Charge <sup>3, 4</sup>	$Q_{gs}$		---	2.4	---	
Gate-Drain Charge <sup>3, 4</sup>	$Q_{gd}$		---	6.8	---	
Turn-On Delay Time <sup>3, 4</sup>	$T_{d(on)}$	$V_{DD}=300V, V_{GS}=10V, R_G=12\Omega, I_D=3.5A$	---	11	---	nS
Rise Time <sup>3, 4</sup>	$T_r$		---	10	---	
Turn-Off Delay Time <sup>3, 4</sup>	$T_{d(off)}$		---	30	---	
Fall Time <sup>3, 4</sup>	$T_f$		---	6	---	
Input Capacitance	$C_{iss}$	$V_{DS}=25V, V_{GS}=0V, F=1\text{MHz}$	---	604	---	pF
Output Capacitance	$C_{oss}$		---	278	---	
Reverse Transfer Capacitance	$C_{rss}$		---	0.6	---	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_S$	$V_G=V_D=0V, \text{Force Current}$	---	---	7	A
Pulsed Source Current	$I_{SM}$		---	---	14	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=3.5A, T_J=25^\circ\text{C}$	---	---	1.2	V
Reverse Recovery Time <sup>3</sup>	$t_{rr}$	$I_S=7A, di/dt=100A/\mu S, T_J=25^\circ\text{C}$	---	262	---	nS
Reverse Recovery Charge <sup>3</sup>	$Q_{rr}$		---	3.5	---	$\mu C$
Peak Reverse Recovery Current	$I_{rrm}$		---	15	---	A

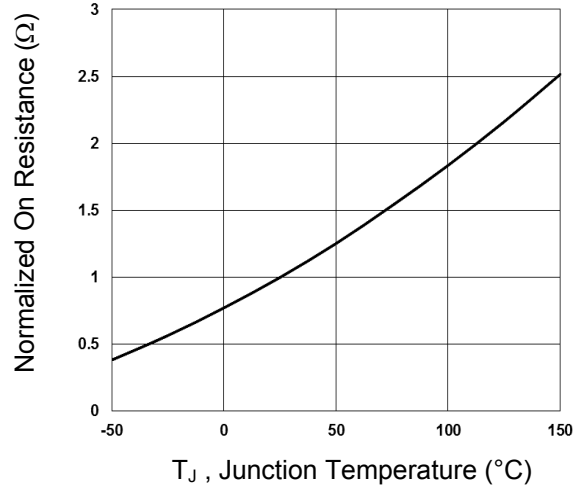
**Notes:**

1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=60V, V_{GS}=4.9A, L=10\text{mH}, R_G=25\Omega, \text{Starting } T_J=25^\circ\text{C}$ .
3. The data tested by pulsed, pulse width  $\leq 300\mu S$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

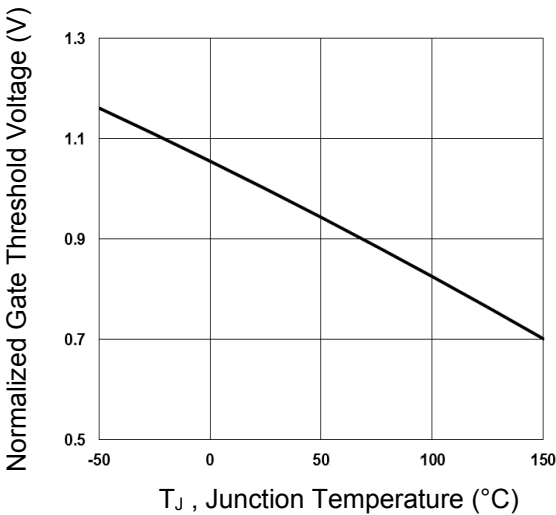
**Typical Electrical and Thermal Characteristic Curves**



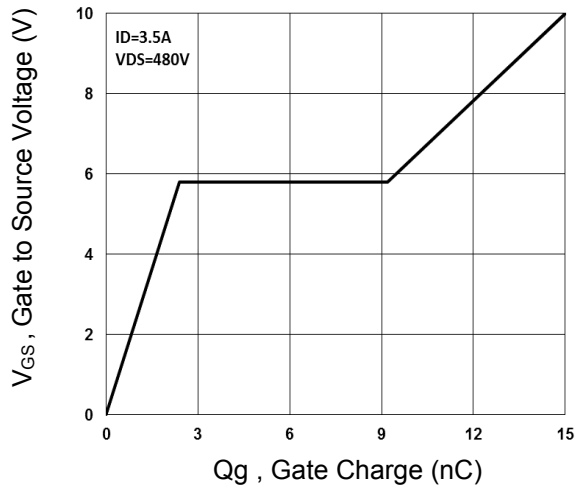
**Fig.1 Continuous Drain Current vs.  $T_c$**



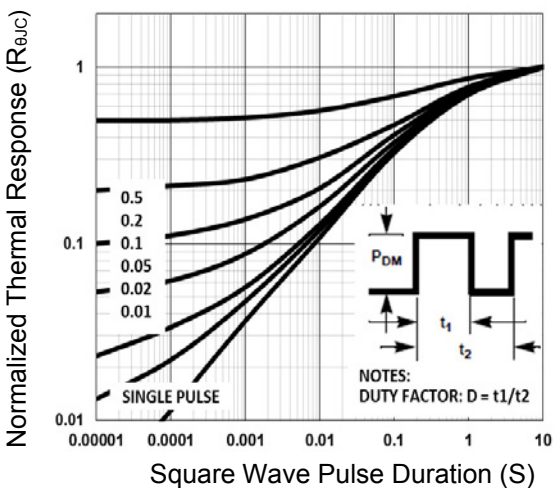
**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_j$**



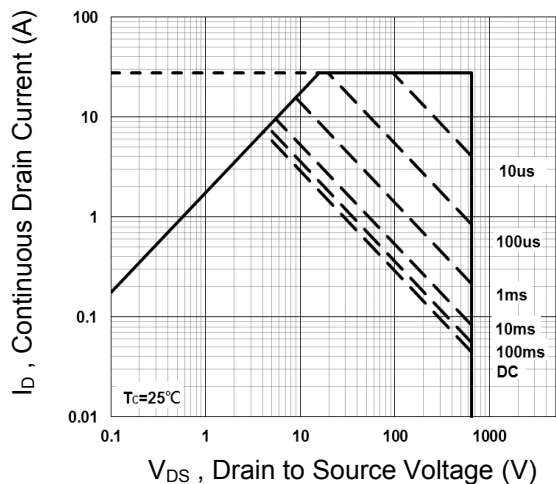
**Fig.3 Normalized  $V_{th}$  vs.  $T_j$**



**Fig.4 Gate Charge Waveform**

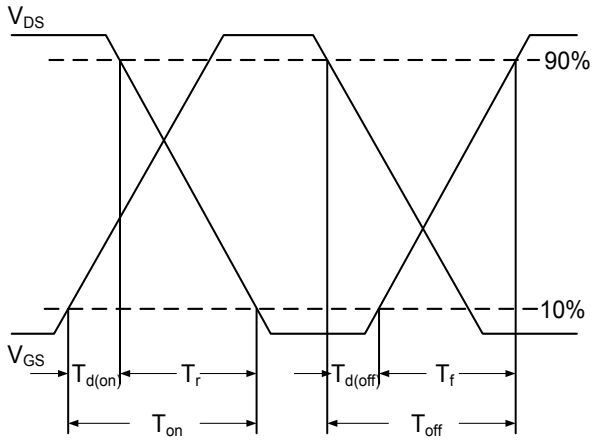


**Fig.5 Normalized Transient Impedance**

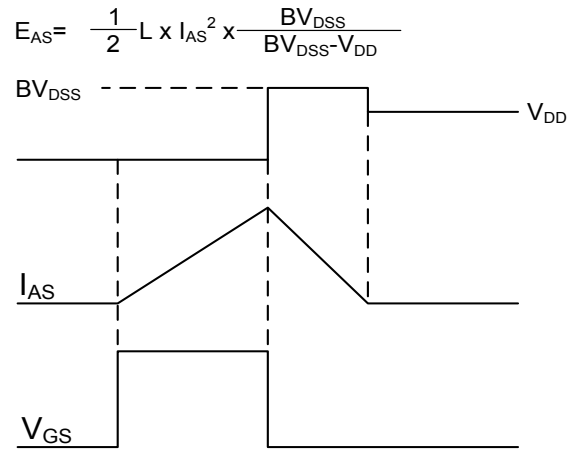


**Fig.6 Maximum Safe Operation Area**

**Typical Electrical and Thermal Characteristic Curves**



**Fig.7 Switching Time Waveform**

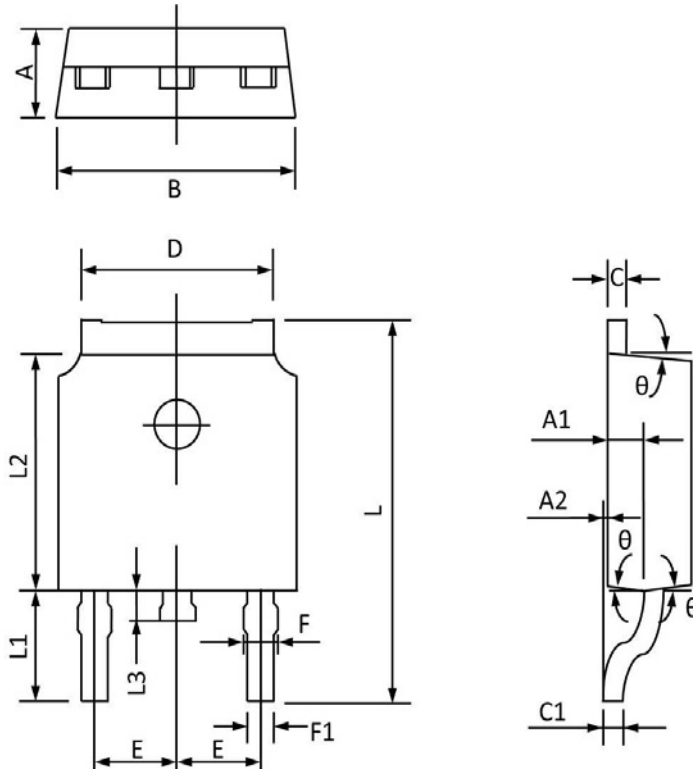


**Fig.8  $E_{AS}$  Waveform**

$$E_{AS} = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

## Package Outline Dimensions

## TO-252 (DPAK)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.400	2.200	0.094	0.087
A1	1.110	0.910	0.044	0.036
A2	0.150	0.000	0.006	0.000
B	6.800	6.400	0.268	0.252
C	0.580	0.450	0.023	0.018
C1	0.580	0.460	0.023	0.018
D	5.500	5.100	0.217	0.201
E	2.386	2.186	0.094	0.086
F	0.940	0.600	0.037	0.024
F1	0.860	0.500	0.034	0.020
L	10.400	9.400	0.409	0.370
L1	3.000	2.400	0.118	0.094
L2	6.200	5.400	0.244	0.213
L3	1.200	0.600	0.047	0.024
θ	9°	3°	9°	3°